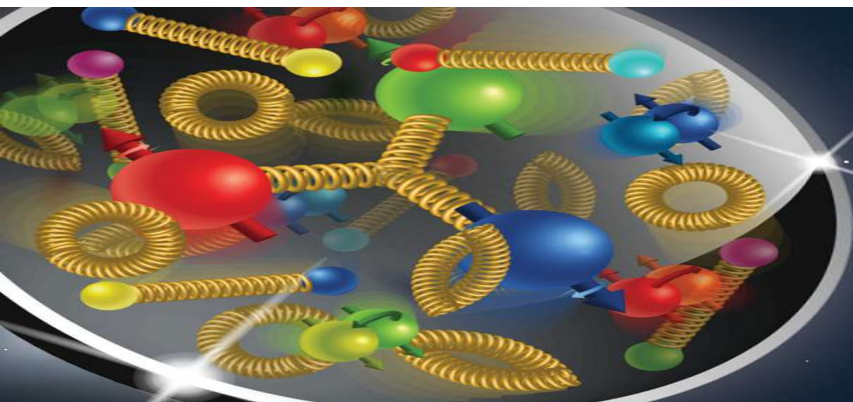


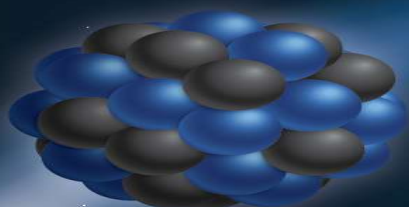


Electron-Ion Collider

BROOKHAVEN
NATIONAL LABORATORY

Jefferson Lab

U.S. DEPARTMENT OF
ENERGY | Office of
Science



Generic RDO Status

ePIC/EICUG Meeting



Electron-Ion Collider

Short overview

- The original concept: to design a reusable FPGA module that is scalable, easy to maintain, and replaceable
- The selected FPGA family is from AMD (or aka Xilinx) – UltraScale+ Arirtx / Kintex, 16nm

Criteria:

- Relatively well-priced FPGAs
- Long-term availability is critical (2045*)
- The scalability is also very important factor
- Support CERN specific signals - CLPS (xROC), 10G (LPGBT, VTRX)
- Keep in house the design and the manufacturing possibility

*<https://www.amd.com/en/products/adaptive-socs-and-fpgas/fpga/artix-ultrascale-plus.html>

UltraScale Architecture Migration Table

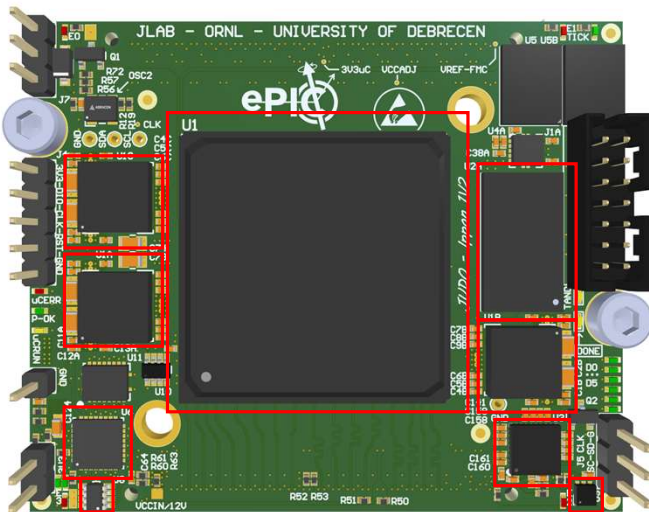
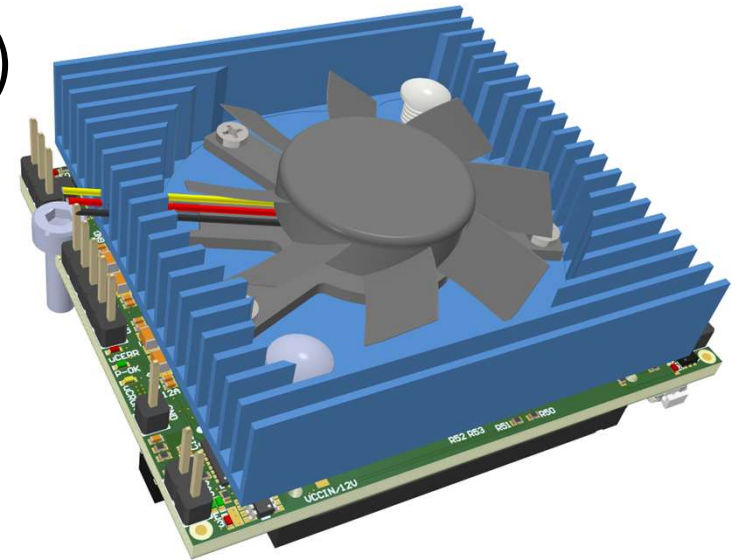
Footprint	Artix™ UltraScale+™					Kintex™ UltraScale™							Kintex UltraScale+					Virtex™ UltraScale								
	AU7P	AU10P	AU15P	AU20P	AU25P	KU025	KU035	KU040	KU060	KU085	KU095	KU115	KU3P	KU5P	KU9P	KU11P	KU13P	KU15P	VU065	VU080	VU095	VU125	VU160	VU190	VU440	VU3P
A289	■																									
A368		■	■																							
B484		■	■																							
C484	■																									
A784								■	■																	
B784				■	■								■	■												
A676								■	■				■	■												
B676		■	■	■	■								■	■												
A900								■	■																	
D900													■	■		■										
E900															■	■		■								
A1156						■	■	■	■		■						■		■							
A1365																										
A1517									■	■		■														
C1517											■								■	■	■					■
D1517												■								■	■	■	■			
E1517																■	■	■								
A1760																		■								
B1760										■	■	■									■	■	■	■		

The planned module - Daughter board (DB)

- Based on these criteria, we need to talk two parts:
 - A relatively small daughter board (DB)
 - And a motherboard (MB) that depends on the application

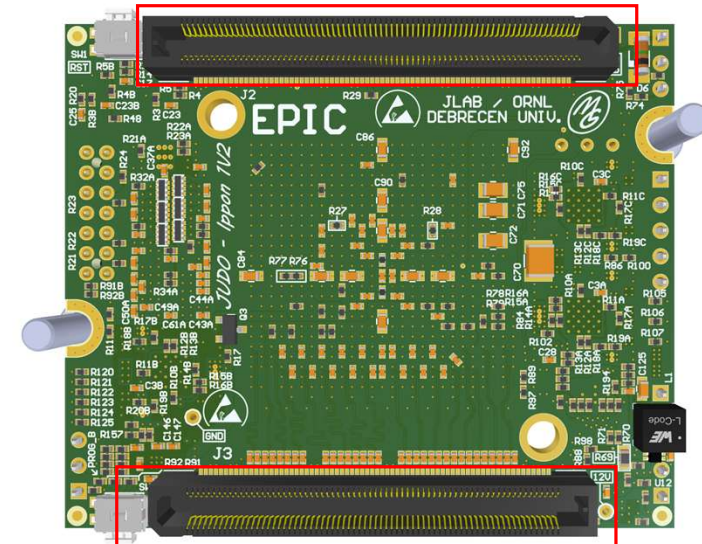
→ Based on previous discussions, the largest Artix (XCAU25P) and the second-largest Kintex (XCKU5P) would be the selected FPGAs. But that could still change...

→ The module size is: 60.5 x 50 mm



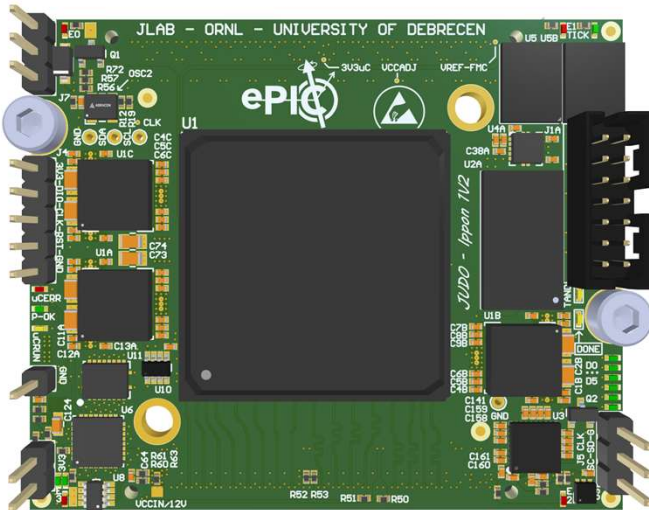
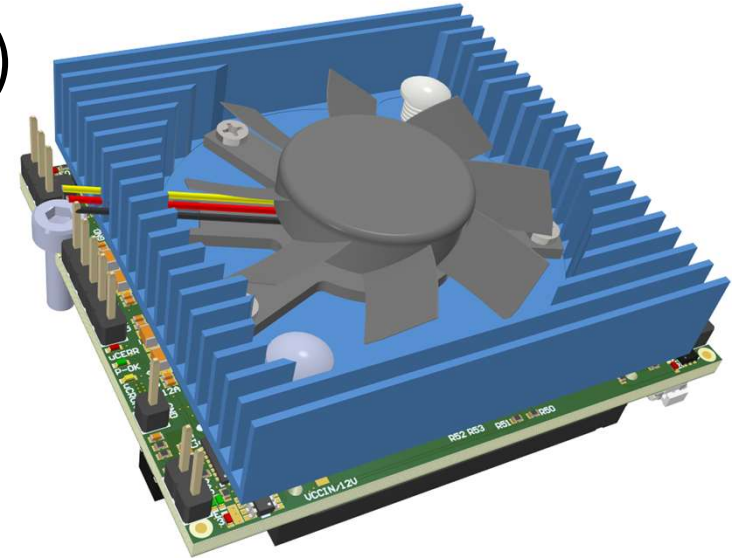
Components

FPGA
Power supplies
System monitoring / Sensors
Clock distribution
Memory
Expansion connectors

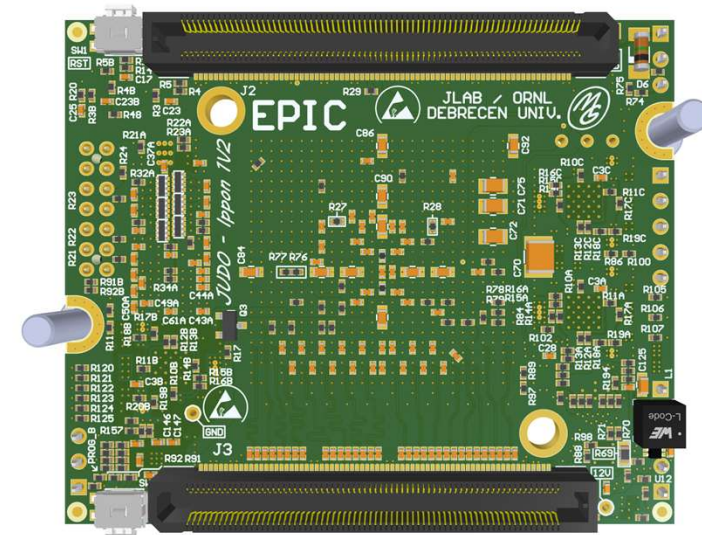


The planned module - Daughter board (DB)

- Aggregation is necessary in many places
- In case of **XCAU25P 12 GTY** are available (Max. 16.3Gbps)*
- In case of **XCKU5P 16 GTY** are available (Max. 32.75Gbps)*



* https://docs.amd.com/api/khub/documents/Fz8MLna3N2KIo_xWN_lv3w/content



The planned module – Motherboard (MB)

- Based on these criteria, we need to talk two parts:
 - A relatively small daughter board (DB)
 - And a motherboard (MB) that depends on the application



Components

Expansion connectors - FPGA

Expansion connectors – FMC

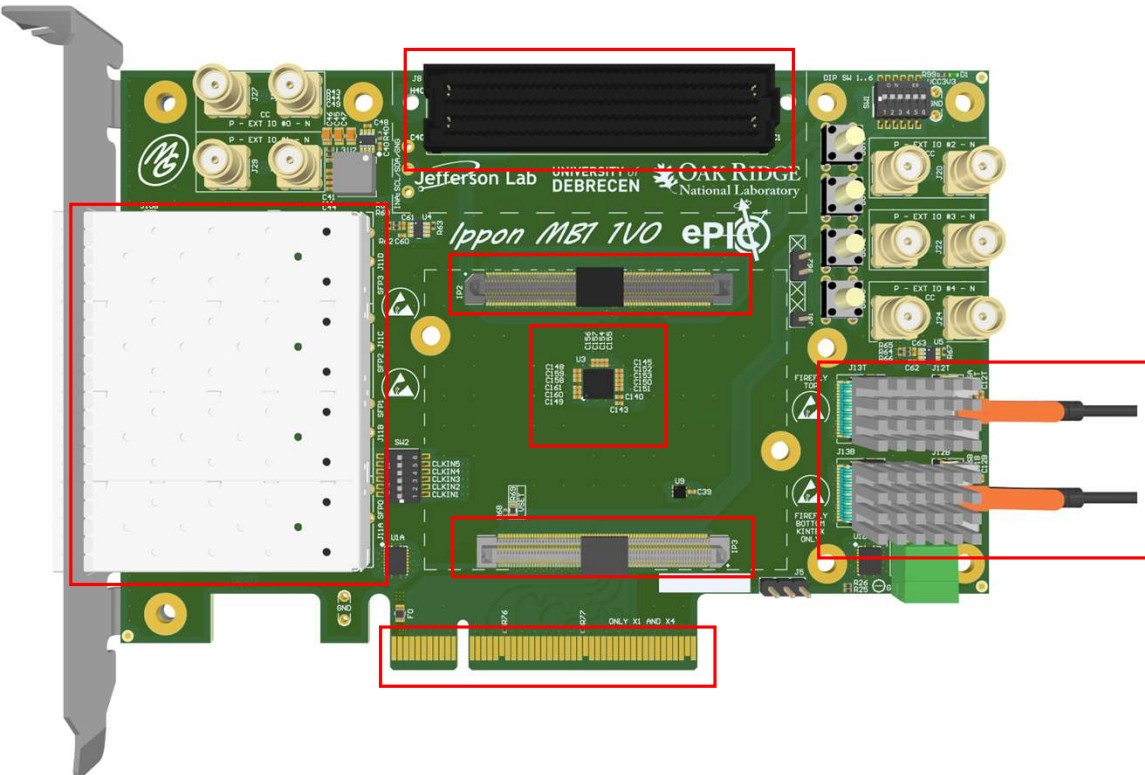
SFP+

FIREFLY

PCIe x4

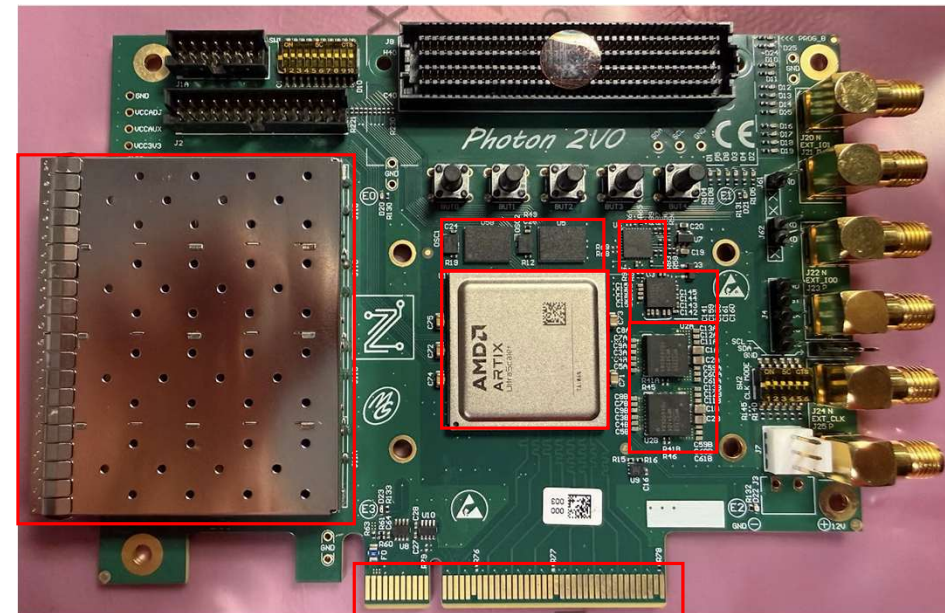
Clock distribution

This MB is designed specially for testing the DB
(And replace the KCU-105)



When are we now?

- The designs - containing simulations also - are ready
 - FPGA translation / IP-s
 - High speed signaling with HyperLynx
 - StackUp planning and optimization with PCB manufacturers
- We have already tested the main components and circuit structures on another panel
 - DCDC converters
 - Clock distribution
 - FPGA Boot
 - System monitoring / controlling
 - 10G SFP+
 - PCIe
- Both boards – DB / MB – are in 99% ready for production
- Production of the first prototypes could begin any time
- No unresolved technical issues, only administrative issues left

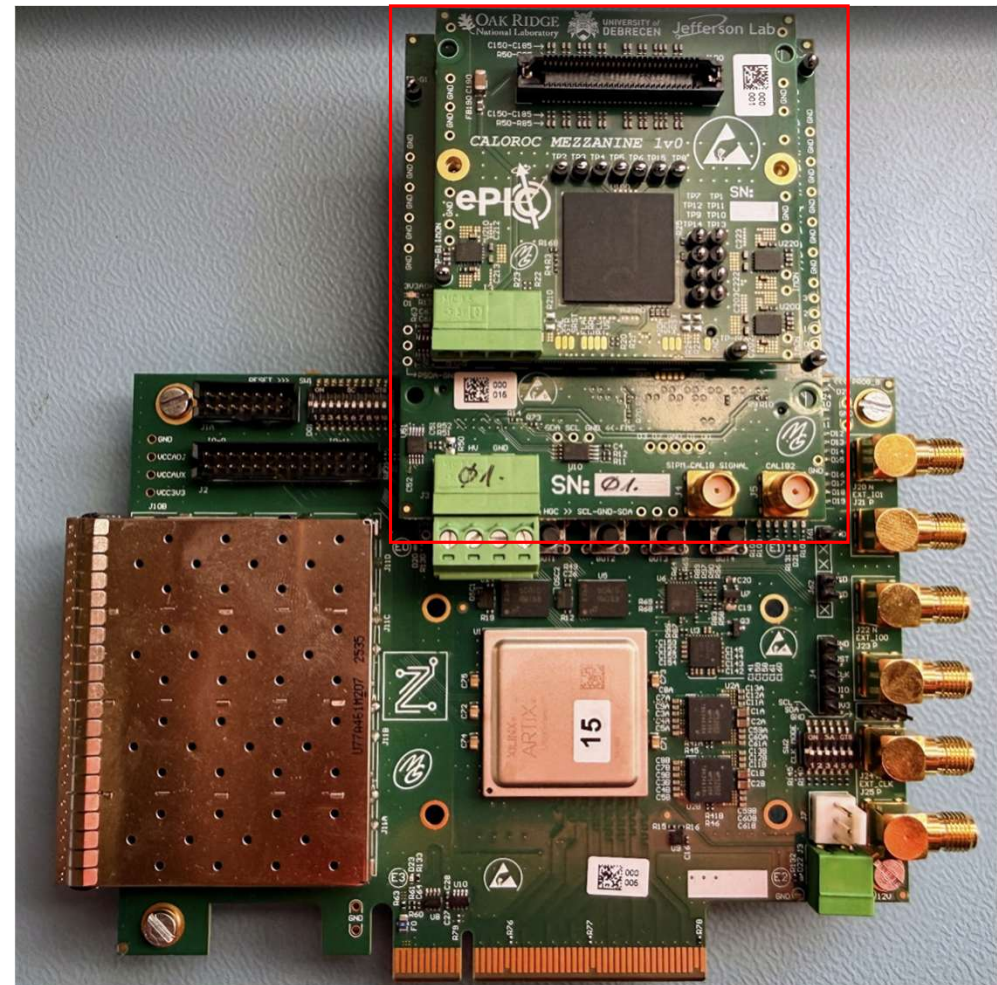


When are we now? – Production (DB, MB)

- Discussions regarding production have concluded (Stackup, Component sources, Panelization)
- Production takes 4–6 weeks
- Steps:
 - First round will be populated only some boards (4-6) with a smaller / cheaper FPGA (*XCAU10P or XCAU15P*)
 - In the second step, we will manufacture several panels, using the final FPGA parts. This will be available for testing.
 - **Please let us know if you would like to participate in the testing!** (A few people have already done so)
 - The start of production has been delayed due to administrative and financial reasons.
 - If everything goes well, the samples will be available in 10-12 weeks (Of course, starting from the time the order is placed)
- Of course, we're open to support other groups with motherboard design as well. If there is a need for it

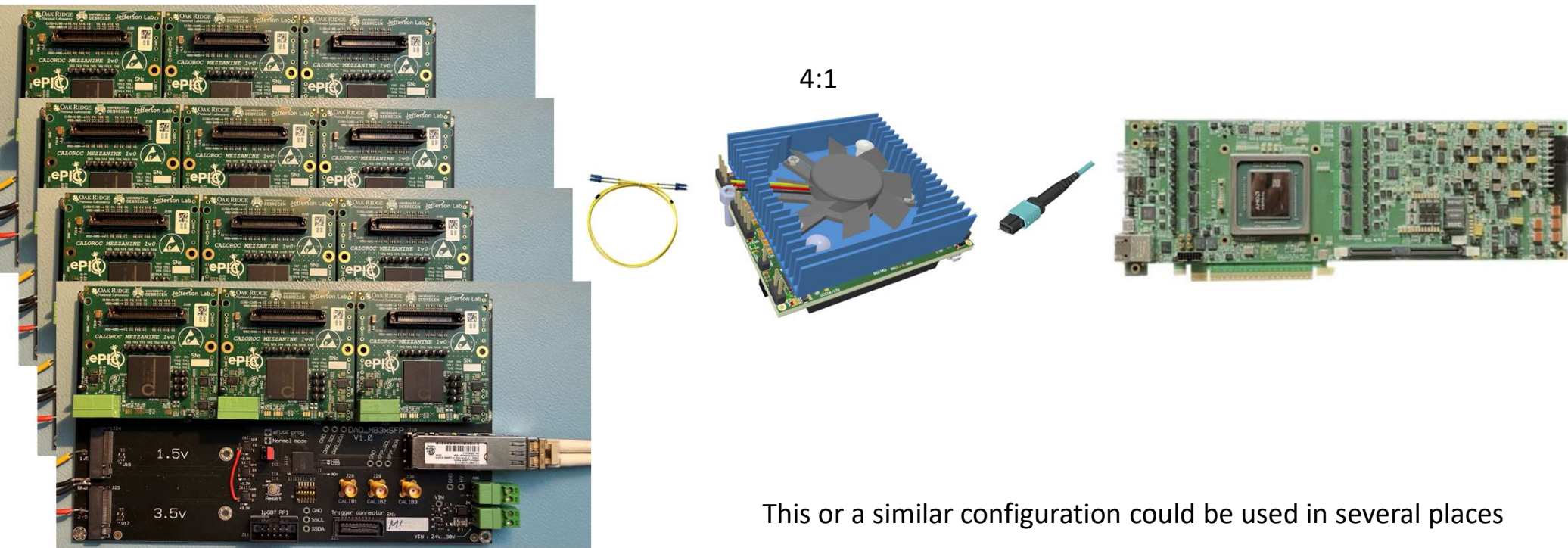
When are we now? - CALOROC

- The CALOROC mezzanine is available
- With A and B version
- This mezzanine will be available in the DB-MB setup
- The FW is currently under development
(On the temporary board shown above.)

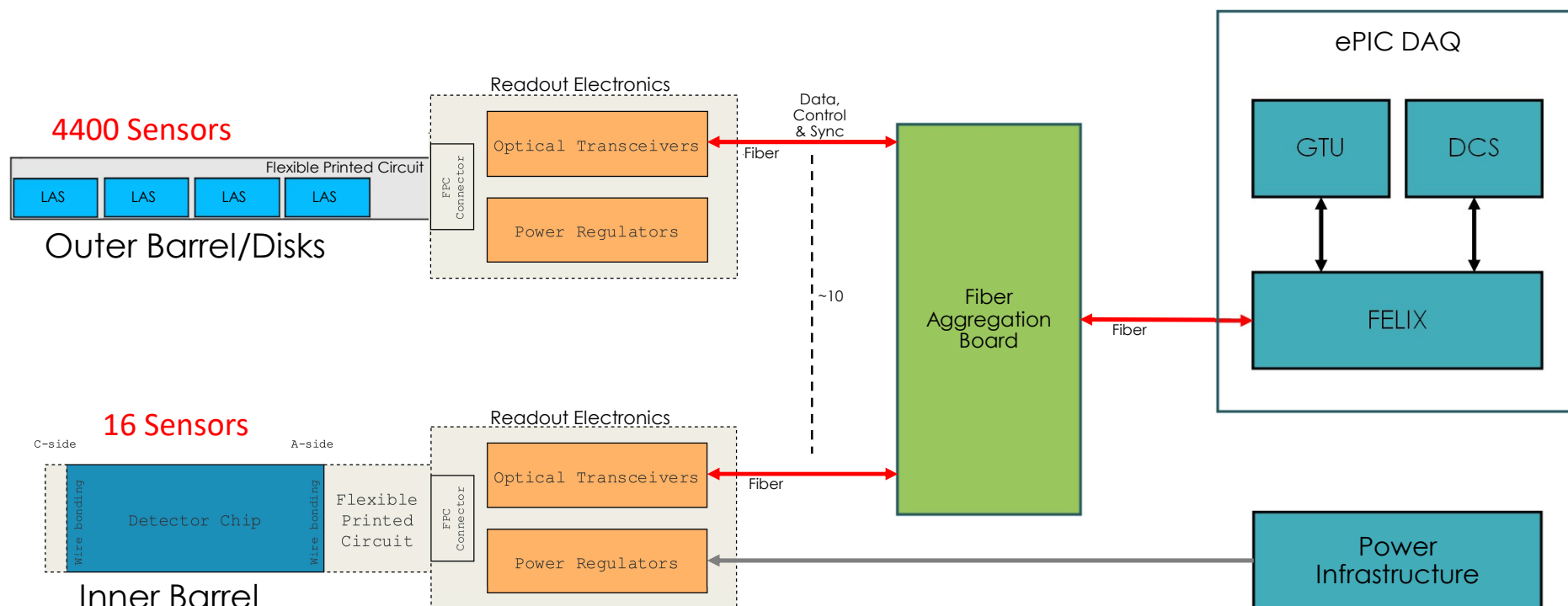


Aggregation – Full Chain test 4:1

- Data receiving from LpGBT chips via 4 lanes at a speed of 10 Gbps
- Do the aggregation with GRDO
- Then forward it to FELIX at a speed of 25 Gbps



MAPS Tracker “SVT” Readout Concept



When are we now? – Rack mounting

- A couple of initial proposals have been drafted
- We're still in the very early stages, and there's still a lot of work to be done

SVT version 1

- Standard 6U height 19" rack from Fischer elektronik
- The space is enough for 10 boards
- BaseBoard size: 233x220 mm

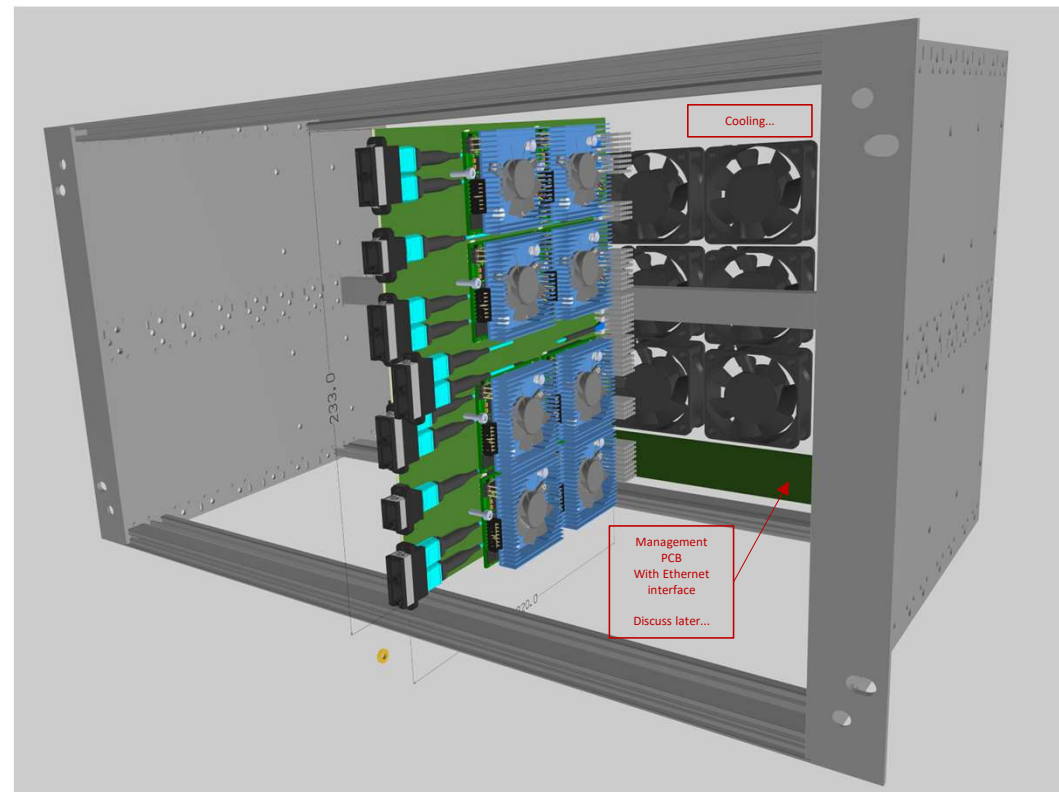
Heights (mm):

- Cooler (passive)	: 10.5
- FPGA	: 3.5
- PCB (RDO)	: 2.0
- BB CON ERF5/ERM5	: 9.0 - 12.0
- BaseBoard PCB	: 1.6
Total	: 26.6 - 29.6

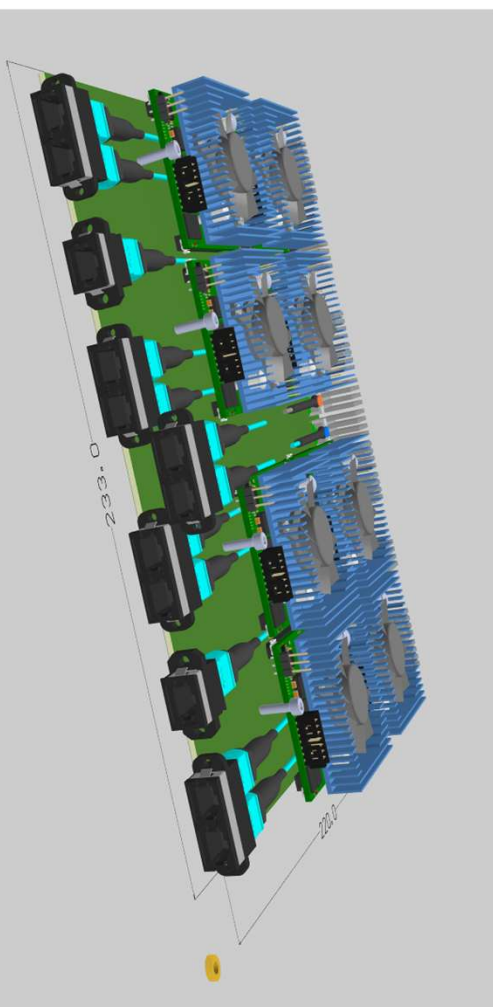
- OPA (Single, Dual) : 25x9.8, 34.8x9.3
- RACK 19 internal width : 431.8

- Available space for / 8 baseboard = 53.97 mm
- **Available space for / 10 baseboard = 43.18 mm**
- Available space for / 12 baseboard = 35.98 mm

- Maybe even 12 is possible...



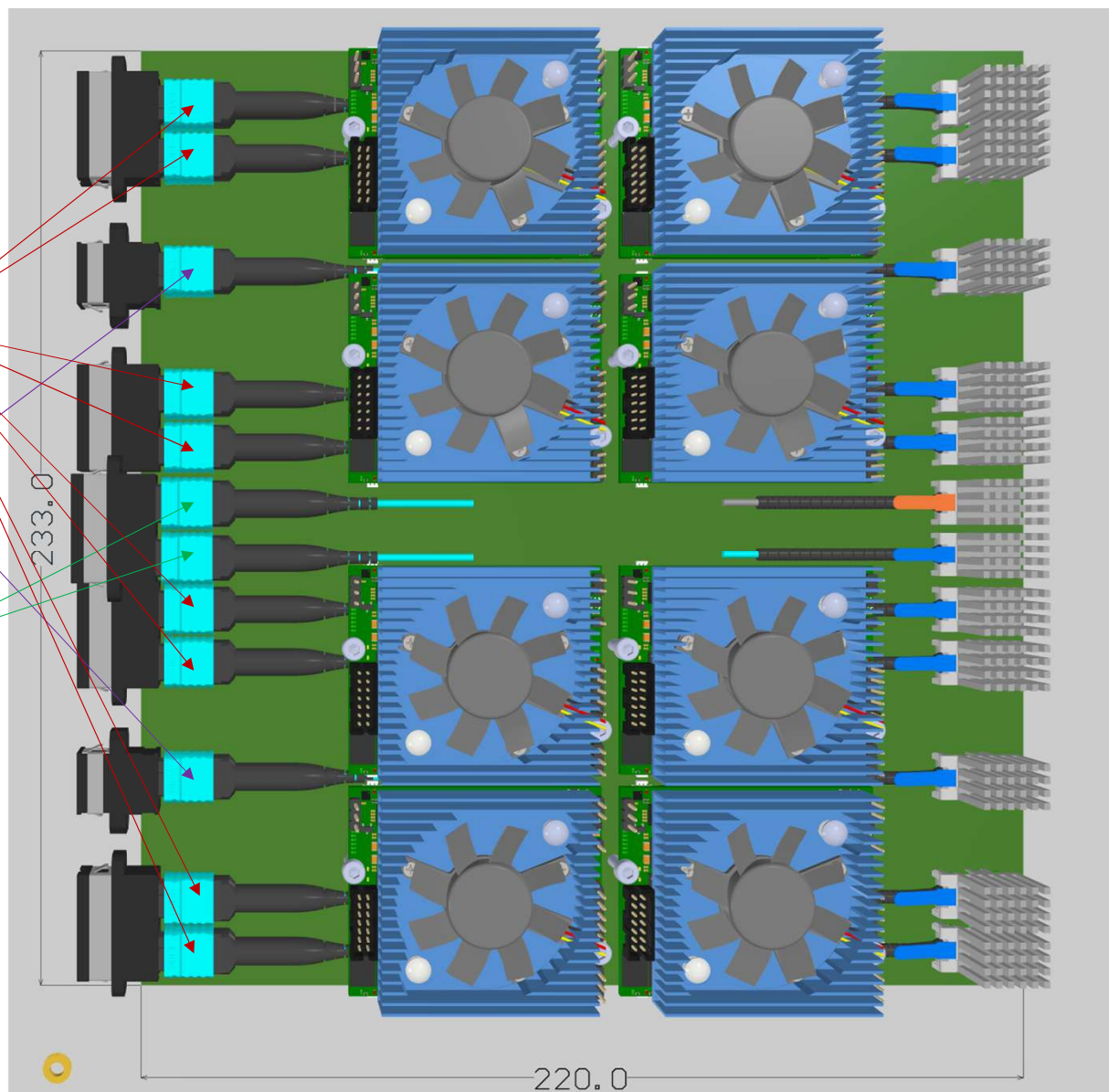
SVT version 1



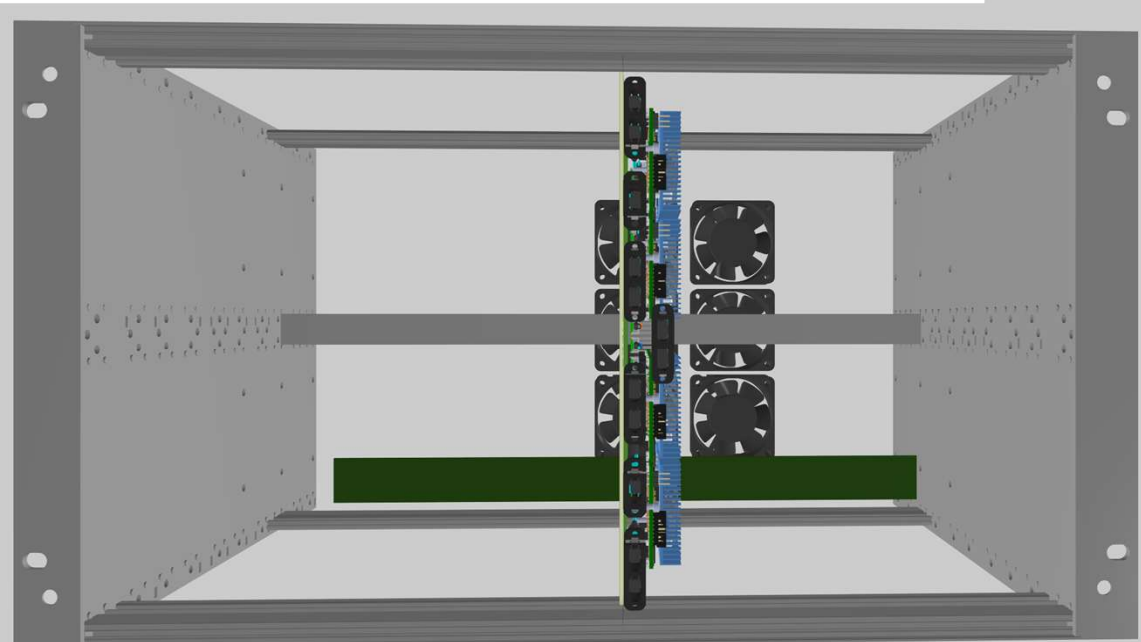
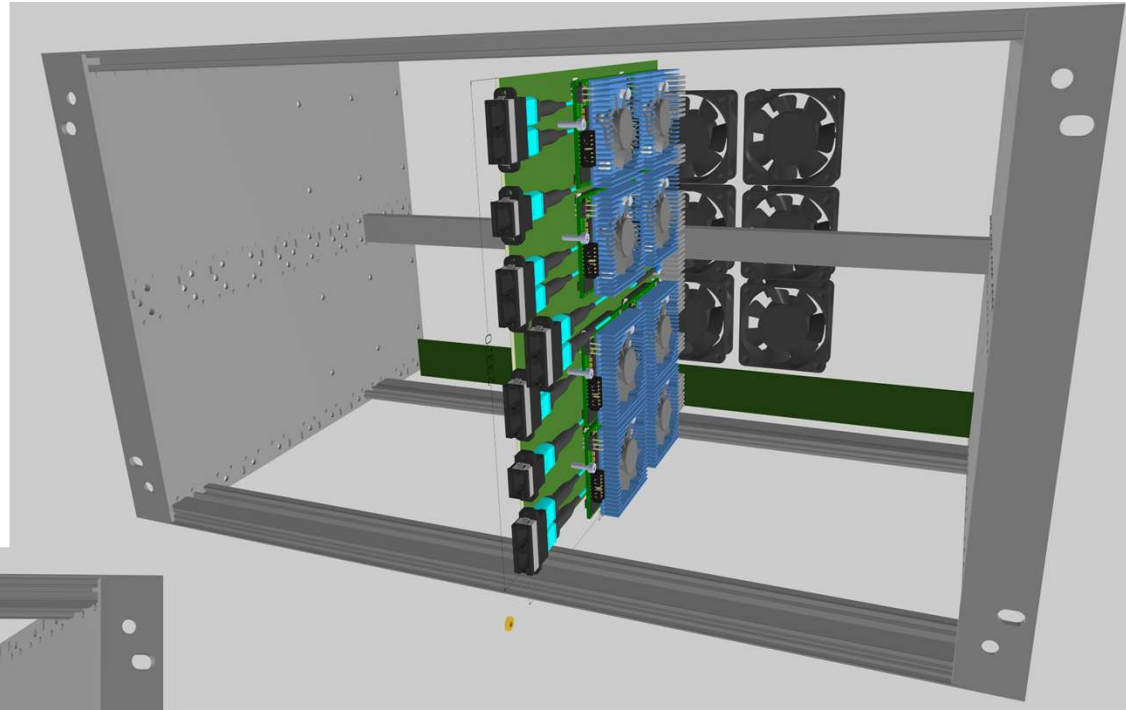
8x
12 RX Only Input (10G)
from detector patch panel
Each RDO has one FIREFLY
connector

2x
TO/FROM FELIX
FIREFLY 25G 4RX / 4TX
Each RDO has one 25G
RX/TX connector to FELIX

Each RDO has 1-1 TX/RX
lines to detector because
slow control...
1-1 TX/RX Output (10G)
to detector patch panel

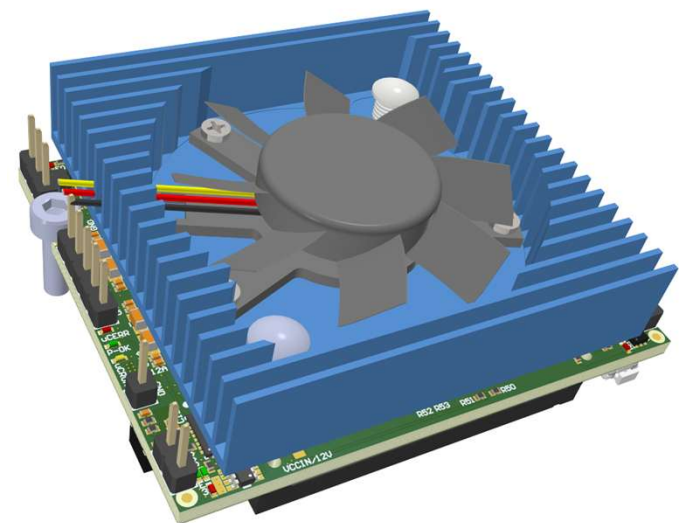


SVT version 1



Summary

- RDO: The design is practically ready to order → Available: 3 month from order
- RDO: If You need test article please let me know
- RDO: the first MB-DB combination is suitable for testing the
 - DB itself (Production test)
 - CALOROC – chip testing
 - CALOROC – calorimeter full chain test - 4:1 aggregation
 - FIREFLY loopback
 - SVT full chain test – Further planning is needed
- Many FW activity needed
- If HW/FW design support needed from us please let me know
- Rack mounting: it's in the brainstorming phase. Discussions and decisions are needed



?

Thanks!

